

## Rotor PCB fabrication details

Artwork files:

• NM-COMM12ROT - Board outline.gbr	Board outline
• NM-COMM12ROT - Bottom Copper (Paste).gbr	Bottom solderpaste
• NM-COMM12ROT - Bottom Copper (Resist).gbr	Bottom soldermask
• NM-COMM12ROT - Bottom Copper.gbr	Layer 4 (bottom)
• NM-COMM12ROT - Bottom Silkscreen.gbr	Bottom silkscreen
• NM-COMM12ROT - DGND Plane (Powerplane).gbr	Layer 2
• NM-COMM12ROT - Drill Data - Through Hole.drl	Drill data
• NM-COMM12ROT - Top Copper (Paste).gbr	Top solderpaste
• NM-COMM12ROT - Top Copper (Resist).gbr	Top soldermask
• NM-COMM12ROT - Top Copper.gbr	Layer 1 (top)
• NM-COMM12ROT - Top Silkscreen.gbr	Top silkscreen
• NM-COMM12ROT - VCC_5V Plane (Powerplane).gbr	Inner layer 3
• NM-COMM12ROT (BOM).csv	BoM
• NM-COMM12ROT (Component Positions CSV).csv	Component positions
• NM-COMM12ROT Layers.rtf	Other

Layers order:

- 1 - Top
- 2 – DGND Plane
- 3 – VCC\_5V Plane
- 4 – Bottom

Board specifications:

- Number of layers: 4
- Width: 20 mm
- Height: 43 mm
- Surface finish: ENIG\*
- Outer layer finish copper: 1 oz\*
- Inner layer copper: 1 oz\*
- Material: FR4\*
- Silkscreen side: Top and Bottom
- Silkscreen color: white\*
- ROHS compliant: yes\*

- Minimum trace width: 6 mil
- Minimum trace spacing: 6 mil
- Solder mask side: Top and Bottom\*
- Solder mask color: green\*
- ITAR: no
- Cutouts: no
- Blind vias: no
- Buried vias: no

\* Can be changed to meet manufacturer's specifications.